

STAUF

— seit 1828 —



STAUF REPAMED

1-component polyurethane liquid repair kit



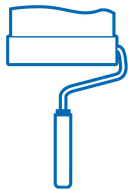
Technical Datasheet

Product number	✓ 124360
Special features	✓ closure of hollow spots ✓ rebonding/repairing
Suitable subfloors	✓ concrete C 25 / 30 according to DIN 1045 (non-skid surface) ✓ calcium sulphate (flow) floors ✓ wooden planks, wood fibre boards ✓ chipboards (P4 to P7), OSB boards (OSB/2 to OSB/4) ✓ unlaminated gypsum fibre boards ✓ cement floors
Application range	✓ Rectification of hollow spots or adhesive bonding of loose wood flooring.
Product properties	✓ suitable on subfloor heating systems ✓ ready for use ✓ good adhesion to various materials ✓ solvent-free
Suitable cleaner	✓ STAUF Solvent cleaner
Color	✓ honey
Required quantities per m ²	✓ Depending on quantity and size of ✓ local separations
Room climate at work site	✓ minimum 15 °C, maximum 75% rel. humidity, preferably max. 65%
Shelf-life	✓ 6 months
Giscode	✓ RU1
Giscode	✓ EC1 plus



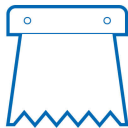
EXAMINATION OF SUBFLOOR

Prior to processing, the subfloor must be checked according to the standard DIN 18356, DIN 18365 or corresponding national standards. The subfloor shall be resistant to pressure and tension, free of cracks, must have sufficient surface strength, be permanently dry, level, clean and free of contaminants that may prevent adhesion, sinter layers etc. In addition, porosity and grip of surface need to be checked. Also check moisture content and absorption of subfloors as well as temperature, air humidity and subfloor temperature.



SUBFLOOR PREPARATION

Before application the hollow spots have to be located by knocking and sensing. The dimensions should be marked with easily removable marking lines (e.g. adhesive tapes, masking tapes). Depending on the dimension and form of the hollow spots one or more boreholes have to be drilled. To avoid a ripping of the wood flooring surface while drilling, the drilling area should be masked with a stable adhesive tape in advance. This also helps to avoid the contact of the repair material leaking out the borehole with the wood flooring surface.



PROCESSING

For drilling and injecting the STAUF Repamed a drill diameter of 4 mm is sufficient. For injection the syringe has to be placed upright on the borehole and the liquid repair material should be injected under constant pressure continuously underneath the wood flooring. In case of several boreholes repeat accordingly. Material leaking out of the boreholes has to be removed immediately. When smaller borehole diameters are needed or for an injection behind borders/baseboards the enclosed needle can be used. The areas injected have to be weight down adequately as the repair material foams easily during the curing process and otherwise the wood flooring can be lifted. After 24 hours the adhesive tapes can be removed. The boreholes can be closed with hot wax, wooden plugs or other suitable materials.



LIMITATION OF LIABILITY

The foregoing representations are based on the results of our most current product and material testing and are of a non-obligatory advisory nature only since we have no control over the actual quality of workmanship, materials used and worksite conditions. As such, they do not constitute an express or implied warranty of any kind. The same applies to our commercial and technical consultation services which are provided free-of-charge and without obligation. Therefore, we strongly recommend that prior on-site testing be conducted to observe and study the suitability of the product for the intended purpose. With the release of this technical information, all prior technical information (technical data sheets, installation recommendations and other information regarding similar purposes) becomes invalid.